Pb Free Plating Product

FFB10UP20STM

10Amperes,200Volts Single Surface Mount Ultra Fast Recovery Epitaxial Diode

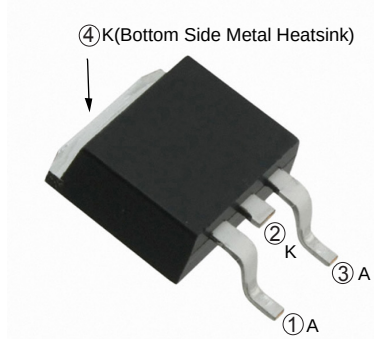
APPLICATION

- Freewheeling, Snubber, Clamp
- Inversion Welder
- PFC
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- Converter & Chopper
- UPS

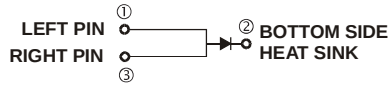
PRODUCT FEATURE

- Ultrafast Recovery Time
- Soft Recovery Characteristics
- Low Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Leakage Current

TO-263/D2PAK(SMD-220)



Internal Configuration



Note: Pins Left & Right must be electrically connected at the printed circuit board.

GENERAL DESCRIPTION

FFB10UP20STM using the lastest FRED FAB process(planar passivation pellet) with ultrafast and soft recovery characteristics.

Absolute Maximum Ratings (per diode) T_a = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetitive Reverse Voltage	200	V
V_{RWM}	Working Peak Reverse Voltage	200	V
V_R	DC Blocking Voltage	200	V
$I_{F(AV)}$	Average Rectified Forward Current @ T_C = 120°C	10	A
I_{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	A
T_J, T_{STG}	Operating Junction and Storage Temperature	- 65 to +150	°C

Thermal Characteristics T_a = 25°C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.0	°C/W

Electrical Characteristics (per diode) T_a = 25°C unless otherwise noted

Symbol	Parameter		Min.	Typ.	Max.	Units
V_{FM} *	I_F = 10A I_F = 10A	T_C = 25 °C T_C = 150 °C	- -	- -	1.15 1.0	V V
I_{RM} *	V_R = 200V V_R = 200V	T_C = 25 °C T_C = 150 °C	- -	- -	100 500	μA μA
t_{rr}	I_F =1A, di/dt = 100A/μs, V_{CC} = 30V I_F =10A, di/dt = 200A/μs, V_{CC} = 130V	T_C = 25 °C T_C = 25 °C	- -	- -	35 45	ns ns
t_a t_b Q_{rr}	I_F =10A, di/dt = 200A/μs, V_{CC} = 130V	T_C = 25 °C T_C = 25 °C T_C = 25 °C	- - -	15 12 36	- - -	ns ns nC
W_{AVL}	Avalanche Energy (L = 20mH)		10	-	-	mJ

* Pulse Test: Pulse Width=300μs, Duty Cycle=2%

Typical Performance Characteristics

Figure 1. Typical Forward Voltage Drop

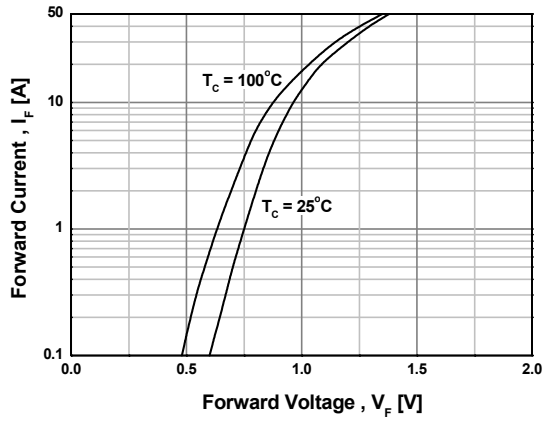


Figure 2. Typical Reverse Current

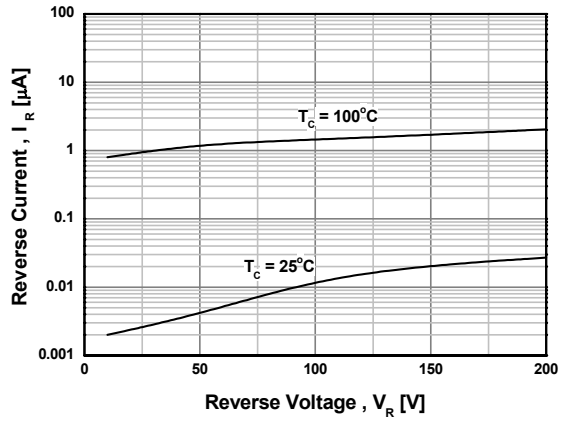


Figure 3. Typical Junction Capacitance

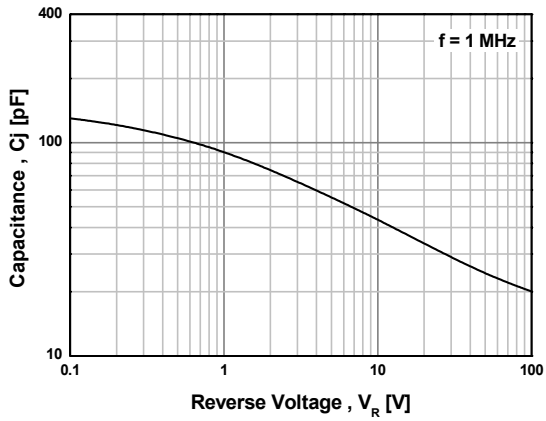


Figure 4. Typical Reverse Recovery Time

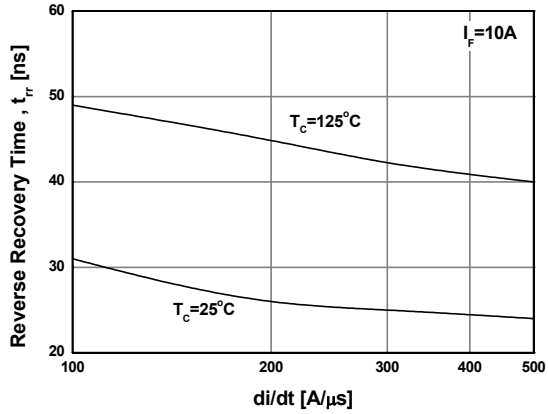


Figure 5. Typical Reverse Recovery Current

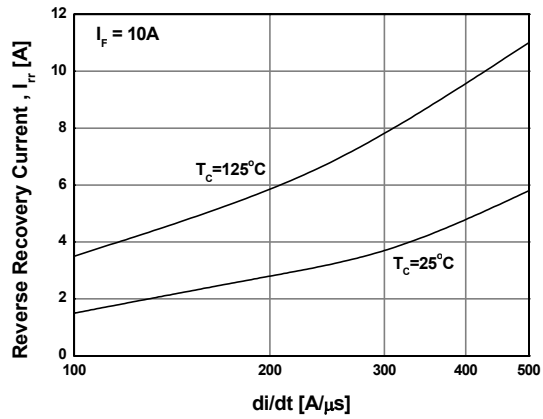
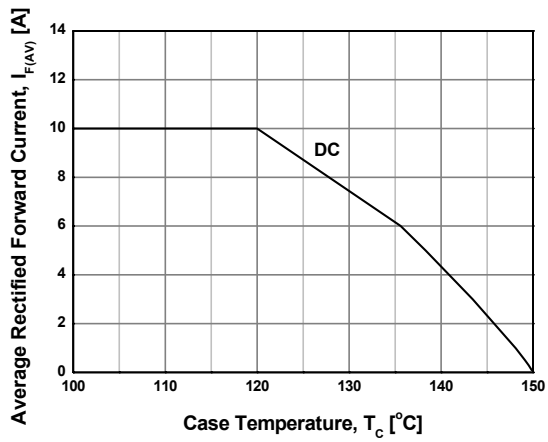
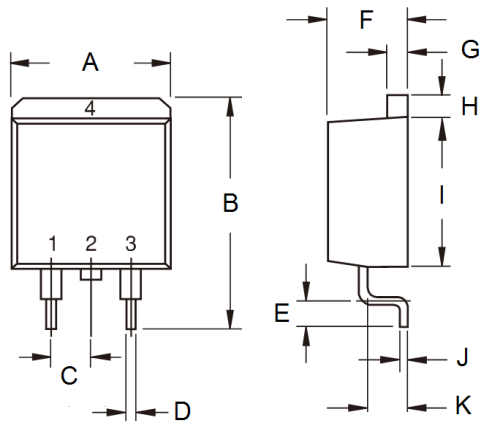


Figure 6. Forward Current Deration Curve

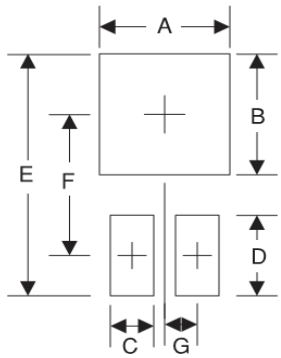


PACKAGE OUTLINE DIMENSIONS **TO-263 (D^2PAK)**



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	-	10.5	-	0.413
B	14.60	15.88	0.575	0.625
C	2.41	2.67	0.095	0.105
D	0.68	0.94	0.027	0.037
E	2.29	2.79	0.090	0.110
F	4.44	4.70	0.175	0.185
G	1.14	1.40	0.045	0.055
H	1.14	1.40	0.045	0.055
I	8.25	9.25	0.325	0.364
J	0.36	0.53	0.014	0.021
K	2.03	2.79	0.080	0.110

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	10.8	0.425
B	8.3	0.327
C	1.1	0.043
D	3.5	0.138
E	16.9	0.665
F	9.5	0.374
G	2.5	0.098

